



## Material Content Data Sheet



<b>Sales Product Name</b>		BGB 707L7ESD E6327		<b>Issued</b>		31. July 2018		
<b>MA#</b>		MA001792310						
<b>Package</b>		PG-TSLP-7-1		<b>Weight*</b>		1.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.11		1085	
	noble metal	gold	7440-57-5	0.007	0.42		4209	
	inorganic material	silicon	7440-21-3	0.059	3.71	4.24	37059	42353
leadframe	non noble metal	nickel	7440-02-0	0.329	20.74	20.74	207432	207432
wire	noble metal	gold	7440-57-5	0.046	2.89	2.89	28855	28855
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.001	0.03		338	
	organic material	carbon black	1333-86-4	0.011	0.68		6752	
	plastics	epoxy resin	-	0.144	9.12		91156	
	inorganic material	silicondioxide	60676-86-0	0.915	57.68	67.51	576986	675232
leadfinish	noble metal	gold	7440-57-5	0.032	2.00	2.00	19960	19960
plating	noble metal	palladium	7440-05-3	0.010	0.62		6208	
	noble metal	gold	7440-57-5	0.032	2.00	2.62	19960	26168
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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